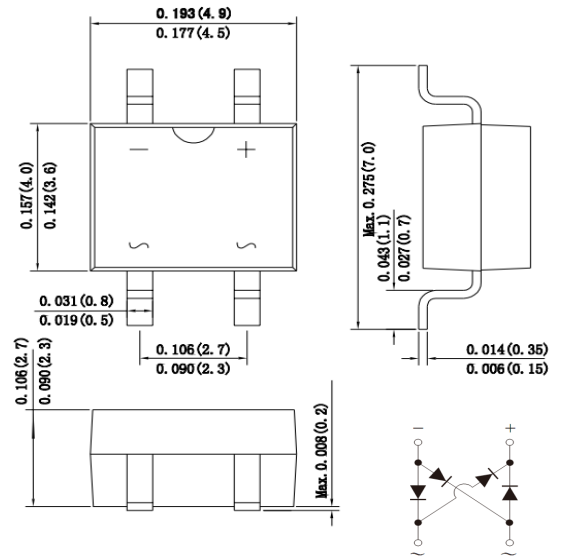


Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Metal-Silicon junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 250°C/10 seconds at terminals

Mechanical Data

- Case** : Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.004 ounce, 0.118 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	KMB 22S	KMB 24S	KMB 26S	KMB 28S	KMB 210S	KMB 215S	KMB 220S	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	20	40	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	70	140	V
Maximum DC blocking voltage	V_{DC}	20	40	60	80	100	150	200	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$ On glass-epoxy P.C.B (Note 1)	I_{AV}	2.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	50.0							A
Rating for fusing ($t=8.3\text{ms}$, $T_a=25^\circ\text{C}$)	I_t^2	10.37							A^2_s
Maximum instantaneous forward voltage at 2.0A	V_F	0.55	0.7	0.85	0.95				V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	0.5 50			0.2 20				mA
Typical thermal resistance	R_{qJA}	85.0							$^\circ\text{C/W}$
Operating junction temperature range	T_J	-55 to +125			-55 to +150				$^\circ\text{C}$
Storage temperature range	T_{STG}	-55 to +150							$^\circ\text{C}$

Note: 1. Mounted on glass epoxy PC board with 1.3*1.3mm solder pad

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

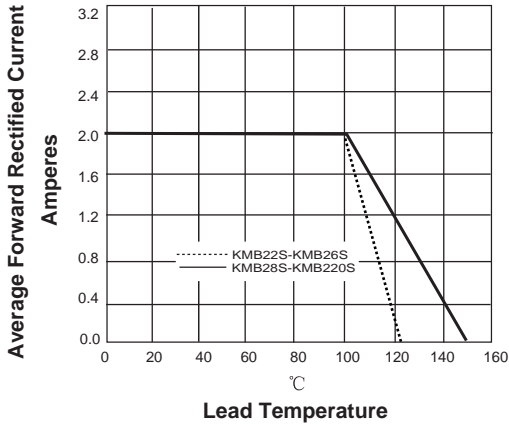


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

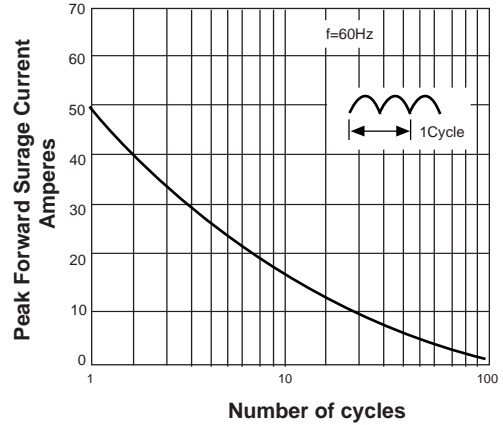


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

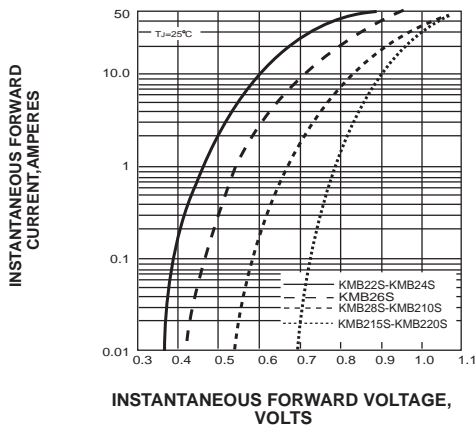
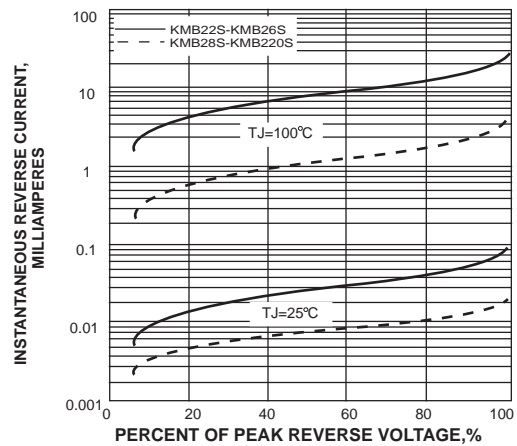
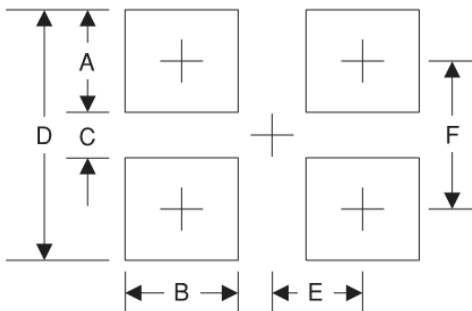


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

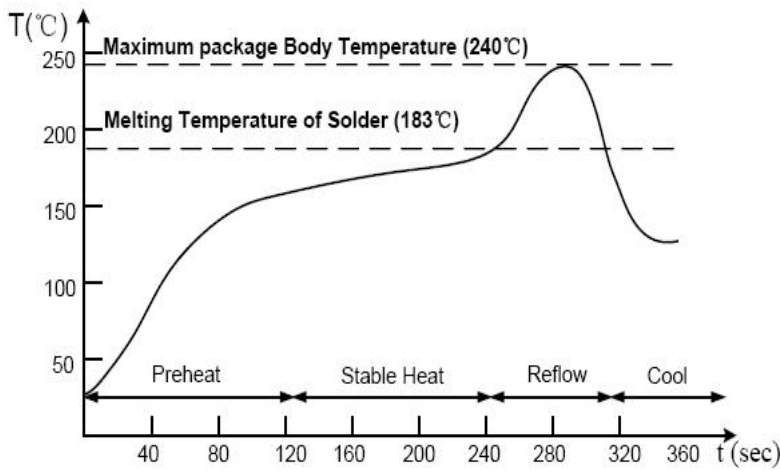


Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.7	0.067
B	1.0	0.039
C	4.40	0.173
D	8.10	0.319
E	1.25	0.049
F	6.30	0.248

Suggested Soldering Temperature Profile

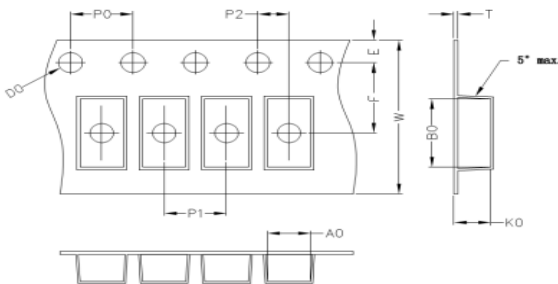


Note

- ◆ Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- ◆ The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- ◆ Devices can be cleaned using standard industry methods and solvents.
- ◆ If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
5.10	7.20	2.88	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	8.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
MBS	13'	330	3	338	6	365*365*360	48